IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An electronic device connecting method comprising:

mounting an electrode of an electronic device closely on a sheet-like porous member having pores, the porous member having a photosensitive layer formed on an inner surface of pores, ~~which produces or eliminates~~ the photosensitive layer producing or eliminating an ion exchange group by irradiation with energy beams on ~~an~~ the inner surface of the pores;

selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted, with energy beams thereby exposing the photosensitive layer to form a latent image in an irradiated or non-irradiated portion of the porous member, the predetermined region including a portion close to the electrode;

after said selectively irradiating, filling pores in the latent image of the porous member with a conductive material to form a conductive portion connected to the electrode; and

bonding the porous member, in which the conductive portion is formed by said filling, to the electronic device.

Claim 2 (Original): An electronic device connecting method as set forth in claim 1, wherein the mounting comprises pressure sensitive adhesion.

Claim 3 (Original): An electronic device connecting method as set forth in claim 1, wherein

the photosensitive layer produces or eliminates an ion exchange group in an irradiated or non-irradiated portion of the photosensitive layer of the porous member to form a pattern of an ion exchange group by the energy beams, and

the conductive portion is formed by selectively absorbing a conductive material or its precursor onto the pattern of the ion exchange group which is formed in the irradiated or non-irradiated portion of the photosensitive layer.

Claim 4 (Original): An electronic device connecting method as set forth in claim 3, further comprising;

electroless plating by using the conductive material or its precursor as a plating nucleus.

Claim 5 (Original): An electronic device connecting method as set forth in claim 1, wherein the conductive portion comprises a region which passes through the porous member, and a region which does not pass through the porous member.

Claim 6 (Original): An electronic device connecting method as set forth in claim 1, wherein the bonding comprises curing after a curing resin impregnates the porous member.

Claims 7-22 (Canceled).